



# STGP7NB60K STGD7NB60K

## N-CHANNEL 7A - 600V TO-220/DPAK SHORT CIRCUIT RATED PowerMESH™ IGBT

TYPE	V <sub>CE(S)</sub>	V <sub>CE(sat)</sub>	I <sub>C</sub>
STGP7NB60K	600 V	< 2.8 V	7 A
STGD7NB60K	600 V	< 2.8 V	7 A

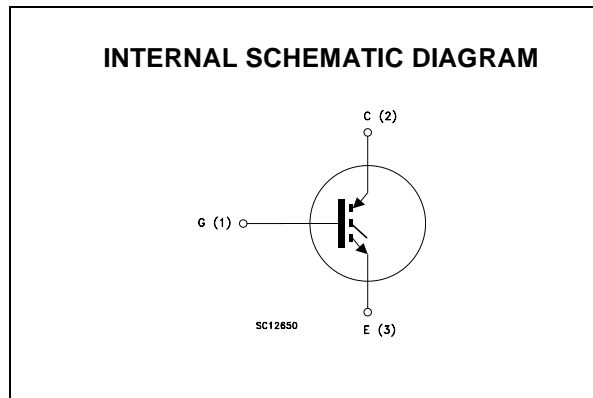
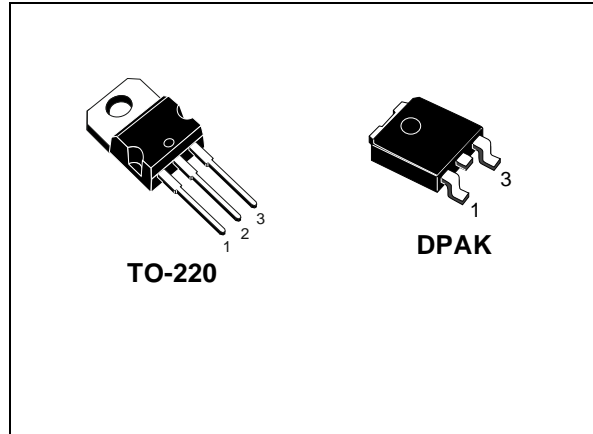
- HIGH INPUT IMPEDANCE (VOLTAGE DRIVEN)
- LOW ON-VOLTAGE DROP (V<sub>cesat</sub>)
- LOW GATE CHARGE
- HIGH CURRENT CAPABILITY
- OFF LOSSES INCLUDE TAIL CURRENT
- HIGH FREQUENCY OPERATION
- SHORT CIRCUIT RATED

### DESCRIPTION

Using the latest high voltage technology based on a patented strip layout, STMicroelectronics has designed an advanced family of IGBTs, the PowerMESH™ IGBTs, with outstanding performances. The suffix "K" identifies a family optimized for high frequency motor control applications with short circuit withstand capability.

### APPLICATIONS

- HIGH FREQUENCY MOTOR CONTROLS
- SMPS AND PFC IN BOTH HARD SWITCHING AND RESONANT TOPOLOGIES



### ORDERING INFORMATION

SALES TYPE	MARKING	PACKAGE	PACKAGING
STGP7NB60K	GP7NB60K	TO-220	TUBE
STGD7NB60KT4	GD7NB60K	DPAK	TAPE & REEL

## STGP7NB60K - STGD7NB60K

### ABSOLUTE MAXIMUM RATINGS

Symbol	Parameter	Value		Unit
		TO-220	DPAK	
$V_{CES}$	Collector-Emitter Voltage ( $V_{GS} = 0$ )	600		V
$V_{ECR}$	Emitter-Collector Voltage	20		V
$V_{GE}$	Gate-Emitter Voltage	$\pm 20$		V
$I_C$	Collector Current (continuous) at $T_C = 25^\circ\text{C}$	14		A
$I_C$	Collector Current (continuous) at $T_C = 100^\circ\text{C}$	7		A
$I_{CM}$ (■)	Collector Current (pulsed)	56		A
$P_{TOT}$	Total Dissipation at $T_C = 25^\circ\text{C}$	80	70	W
	Derating Factor	0.64	0.56	W/ $^\circ\text{C}$
$T_{stg}$	Storage Temperature	- 55 to 150		$^\circ\text{C}$
$T_j$	Max. Operating Junction Temperature	150		$^\circ\text{C}$

(■) Pulse width limited by safe operating area

### THERMAL DATA

		TO-220	DPAK	
Rthj-case	Thermal Resistance Junction-case Max	1.56	1.78	$^\circ\text{C}/\text{W}$
Rthj-amb	Thermal Resistance Junction-ambient Max	62.5	100	$^\circ\text{C}/\text{W}$

### ELECTRICAL CHARACTERISTICS ( $T_{CASE} = 25^\circ\text{C}$ UNLESS OTHERWISE SPECIFIED)

OFF

Symbol	Parameter	Test Conditions	Min.	Typ.	Max.	Unit
$V_{BR(CES)}$	Collector-Emitter Breakdown Voltage	$I_C = 250\ \mu\text{A}$ , $V_{GE} = 0$	600			V
$I_{CES}$	Collector cut-off ( $V_{GE} = 0$ )	$V_{CE} = \text{Max Rating}$ , $T_C = 25^\circ\text{C}$ $V_{CE} = \text{Max Rating}$ , $T_C = 125^\circ\text{C}$			50 500	$\mu\text{A}$ $\mu\text{A}$
$I_{GES}$	Gate-Emitter Leakage Current ( $V_{CE} = 0$ )	$V_{GE} = \pm 20\text{V}$ , $V_{CE} = 0$			$\pm 100$	nA

ON

Symbol	Parameter	Test Conditions	Min.	Typ.	Max.	Unit
$V_{GE(th)}$	Gate Threshold Voltage	$V_{CE} = V_{GE}$ , $I_C = 250\ \mu\text{A}$	5		7	V
$V_{CE(sat)}$	Collector-Emitter Saturation Voltage	$V_{GE} = 15\text{V}$ , $I_C = 7\ \text{A}$ $V_{GE} = 15\text{V}$ , $I_C = 7\ \text{A}$ , $T_C = 125^\circ\text{C}$		2.3 1.9	2.8	V V

**ELECTRICAL CHARACTERISTICS (CONTINUED)**  
**DYNAMIC**

Symbol	Parameter	Test Conditions	Min.	Typ.	Max.	Unit
$g_{fs}$	Forward Transconductance	$V_{CE} = 15\text{ V}$ , $I_C = 7\text{ A}$		3.7		S
$C_{ies}$ $C_{oes}$ $C_{res}$	Input Capacitance Output Capacitance Reverse Transfer Capacitance	$V_{CE} = 25\text{ V}$ , $f = 1\text{ MHz}$ , $V_{GE} = 0$		495 77 13		pF pF pF
$Q_g$ $Q_{ge}$ $Q_{gc}$	Total Gate Charge Gate-Emitter Charge Gate-Collector Charge	$V_{CE} = 480\text{ V}$ , $I_C = 7\text{ A}$ , $V_{GE} = 15\text{ V}$		32.7 5.9 18.3	45	nC nC nC
tscw	Short Circuit Withstand Time	$V_{ce} = 0.5 V_{BR}(CES)$ , $V_{GE} = 15\text{ V}$ $T_j = 125^\circ\text{C}$ , $R_G = 10\ \Omega$	10			$\mu\text{s}$

**SWITCHING ON**

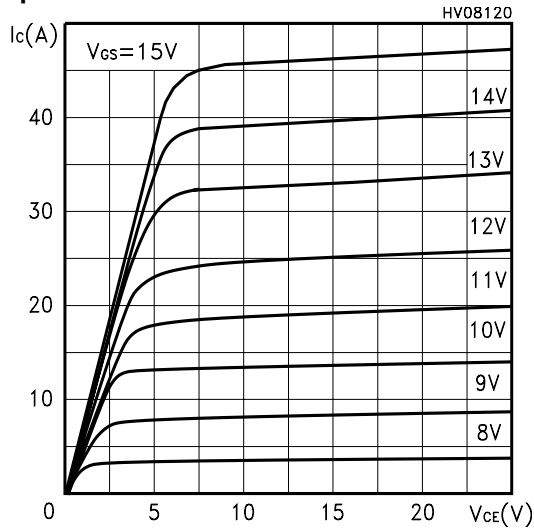
Symbol	Parameter	Test Conditions	Min.	Typ.	Max.	Unit
$t_{d(on)}$	Turn-on Delay Time	$V_{CC} = 480\text{ V}$ , $I_C = 7\text{ A}$		15		ns
$t_r$	Rise Time	$R_G = 10\ \Omega$ , $V_{GE} = 15\text{ V}$		6		ns
$(di/dt)_{on}$ Eon	Turn-on Current Slope Turn-on Switching Losses	$V_{CC} = 480\text{ V}$ , $I_C = 7\text{ A}$ , $R_G = 10\ \Omega$ $V_{GE} = 15\text{ V}$ , $T_j = 125^\circ\text{C}$		980 95		A/ $\mu\text{s}$ $\mu\text{J}$

**SWITCHING OFF**

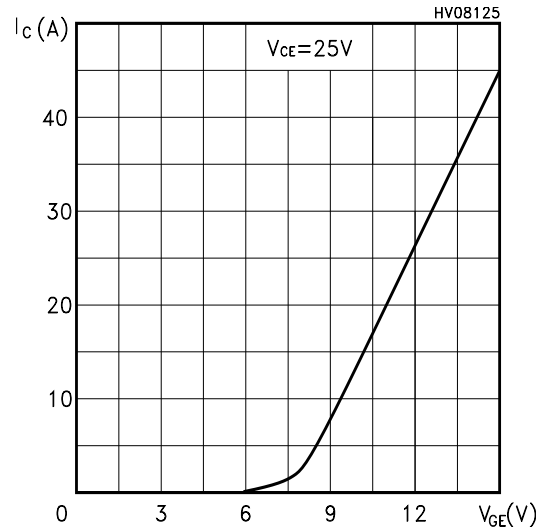
Symbol	Parameter	Test Conditions	Min.	Typ.	Max.	Unit
$t_c$	Cross-over Time	$V_{CC} = 480\text{ V}$ , $I_C = 7\text{ A}$ ,		105		ns
$t_r(V_{off})$	Off Voltage Rise Time	$R_{GE} = 10\ \Omega$ , $V_{GE} = 15\text{ V}$		30		ns
$t_{d(off)}$	Delay Time			50		ns
$t_f$	Fall Time			100		ns
$E_{off(**)}$	Turn-off Switching Loss			140		$\mu\text{J}$
$E_{ts}$	Total Switching Loss			200		$\mu\text{J}$
$t_c$	Cross-over Time	$V_{CC} = 480\text{ V}$ , $I_C = 7\text{ A}$ ,		227		ns
$t_r(V_{off})$	Off Voltage Rise Time	$R_{GE} = 10\ \Omega$ , $V_{GE} = 15\text{ V}$		68		ns
$t_{d(off)}$	Delay Time	$T_j = 125^\circ\text{C}$		52		ns
$t_f$	Fall Time			150		ns
$E_{off(**)}$	Turn-off Switching Loss			300		$\mu\text{J}$
$E_{ts}$	Total Switching Loss			395		$\mu\text{J}$

(\*\*) Losses include Also the Tail (Jedec Standardization)

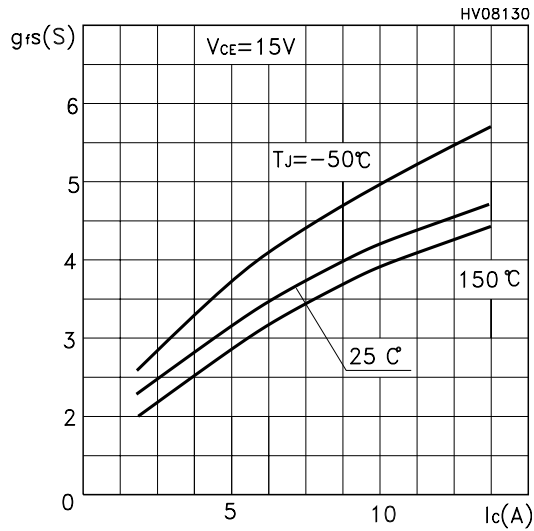
Output Characteristics



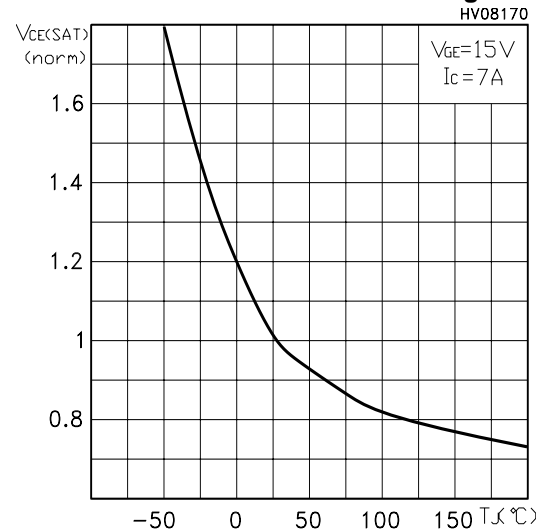
Transfer Characteristics



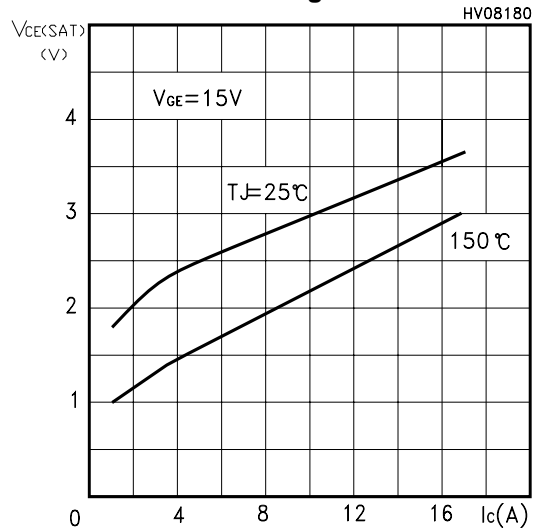
Transconductance



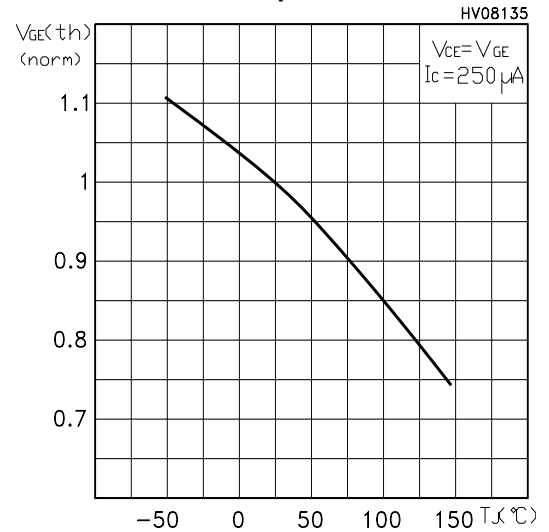
Normalized Collector-Emitter On Voltage



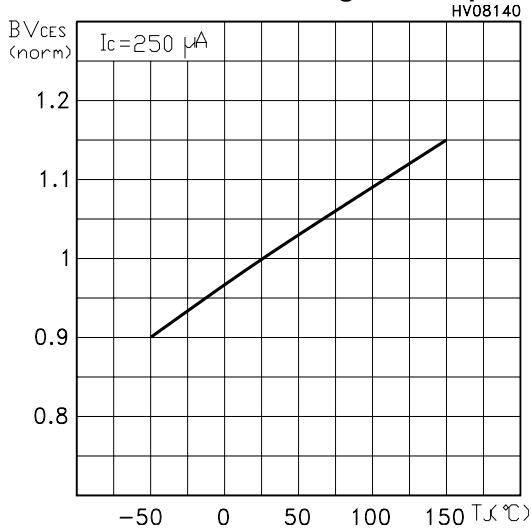
Collector-Emitter On Voltage vs Collector Current



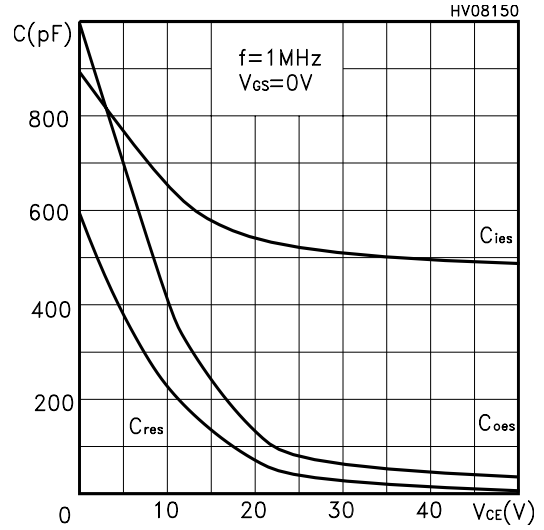
Gate Threshold vs Temperature



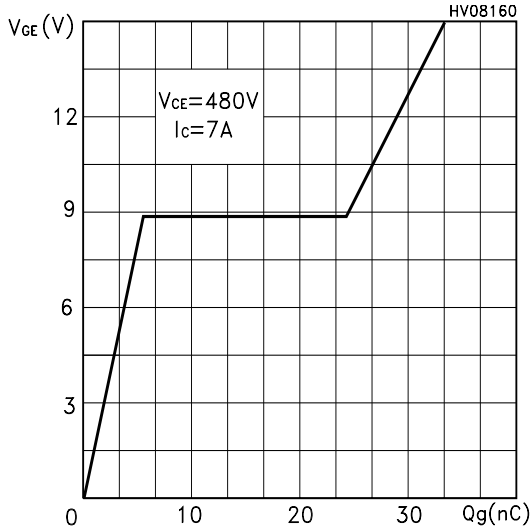
Normalized Breakdown Voltage vs Temperature



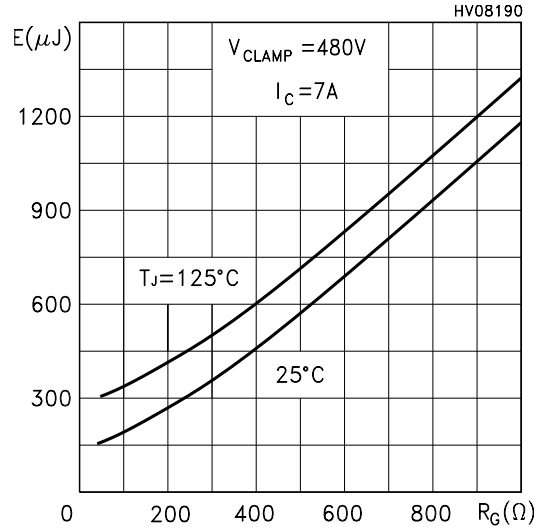
Capacitance Variations



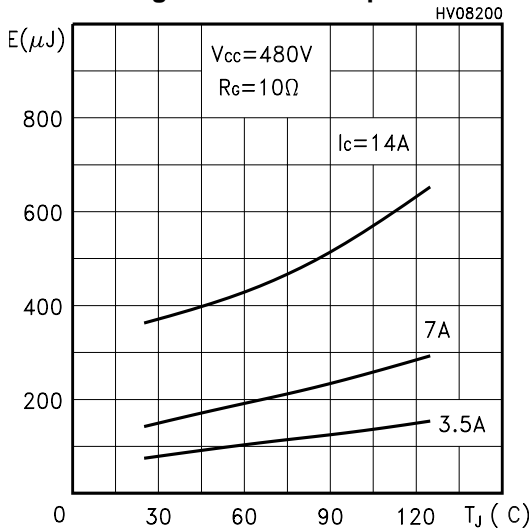
Gate Charge vs Gate-Emitter Voltage



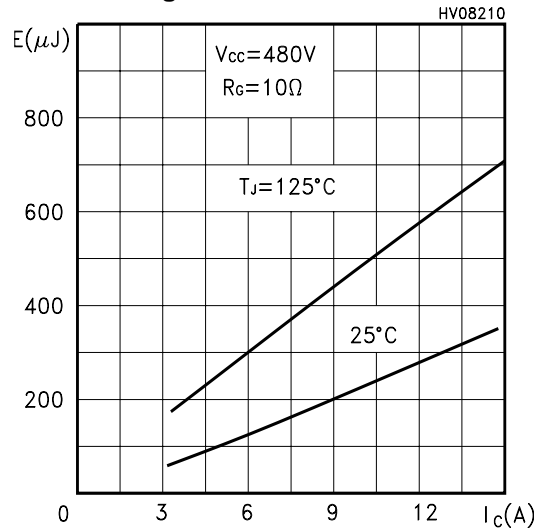
Total Switching Losses vs Gate Resistance



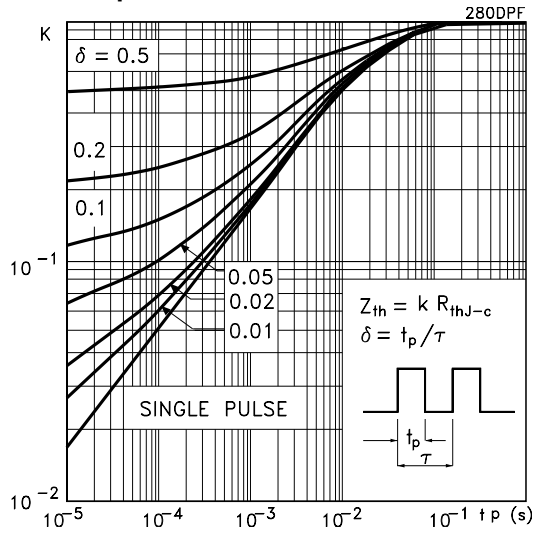
Total Switching Losses vs Temperature



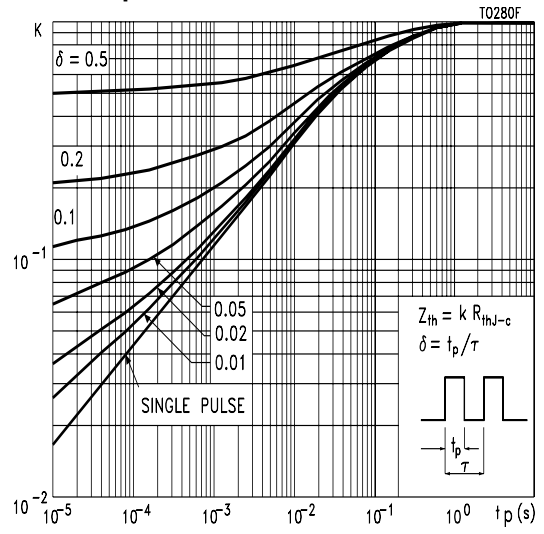
Total Switching Losses vs Collector Current



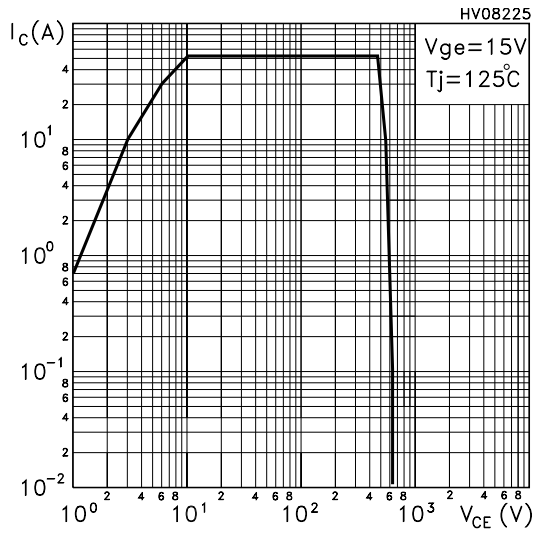
Thermal Impedance for DPAK



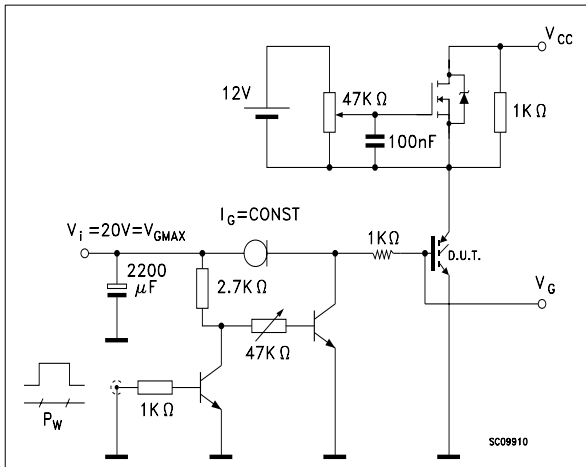
Thermal Impedance for TO-220



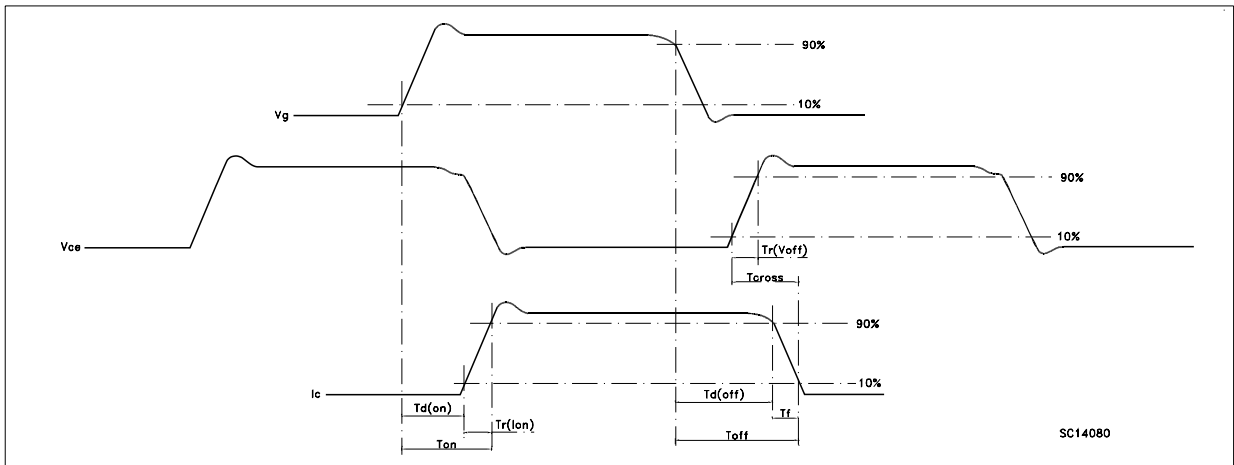
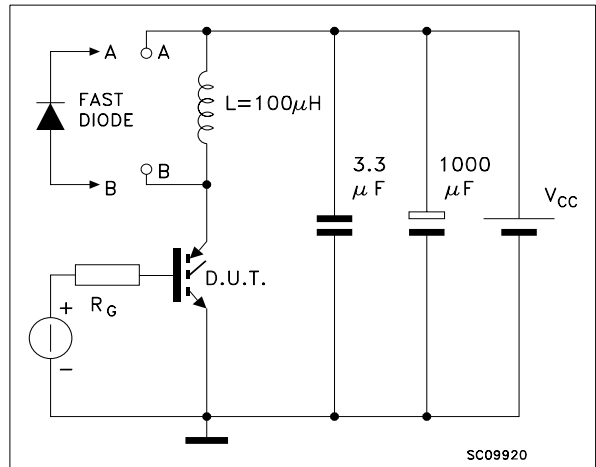
Turn-Off SOA



**Fig. 1: Gate Charge test Circuit**

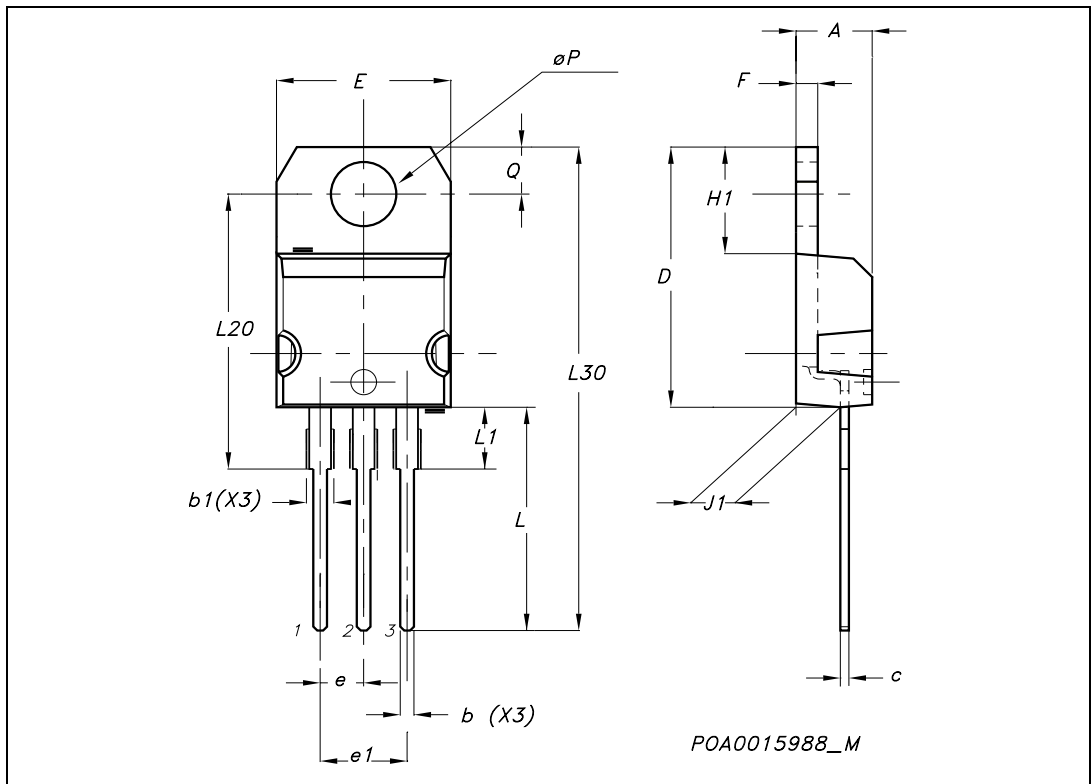


**Fig. 2: Test Circuit For Inductive Load Switching**



**TO-220 MECHANICAL DATA**

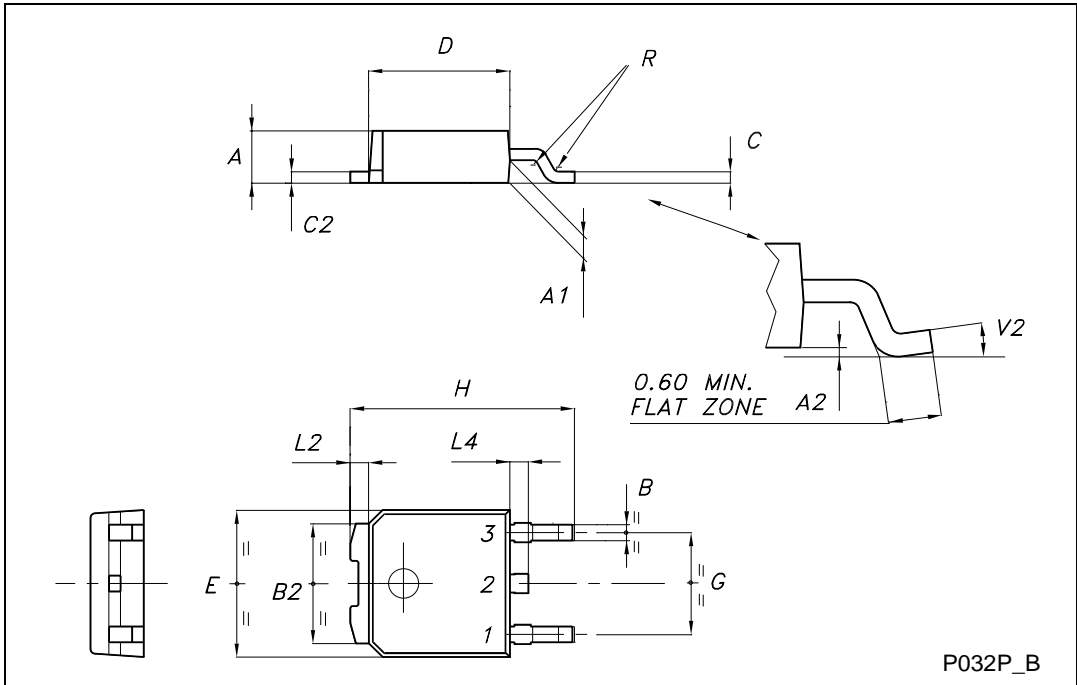
DIM.	mm.			inch		
	MIN.	TYP.	MAX.	MIN.	TYP.	MAX.
A	4.40		4.60	0.173		0.181
b	0.61		0.88	0.024		0.034
b1	1.15		1.70	0.045		0.066
c	0.49		0.70	0.019		0.027
D	15.25		15.75	0.60		0.620
E	10		10.40	0.393		0.409
e	2.40		2.70	0.094		0.106
e1	4.95		5.15	0.194		0.202
F	1.23		1.32	0.048		0.052
H1	6.20		6.60	0.244		0.256
J1	2.40		2.72	0.094		0.107
L	13		14	0.511		0.551
L1	3.50		3.93	0.137		0.154
L20		16.40			0.645	
L30		28.90			1.137	
øP	3.75		3.85	0.147		0.151
Q	2.65		2.95	0.104		0.116



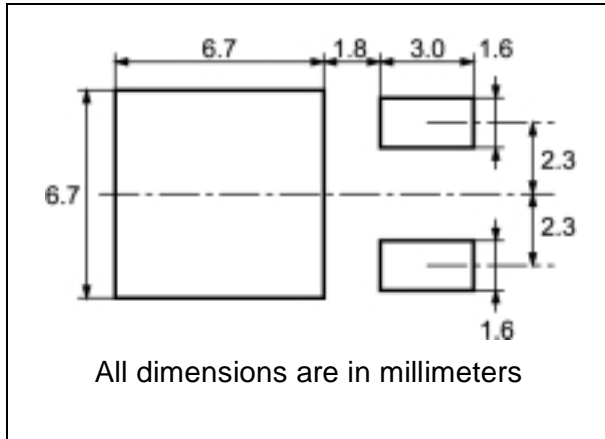


**TO-252 (DPAK) MECHANICAL DATA**

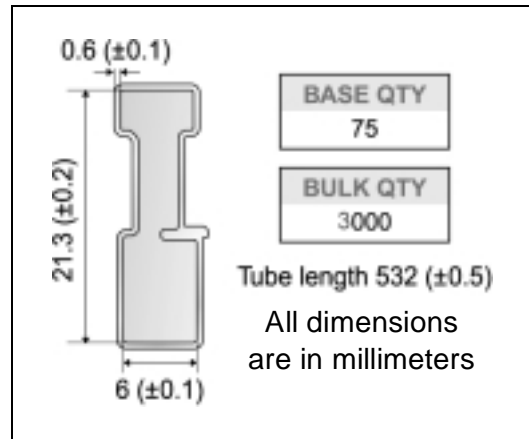
DIM.	mm			inch		
	MIN.	TYP.	MAX.	MIN.	TYP.	MAX.
A	2.20		2.40	0.087		0.094
A1	0.90		1.10	0.035		0.043
A2	0.03		0.23	0.001		0.009
B	0.64		0.90	0.025		0.035
B2	5.20		5.40	0.204		0.213
C	0.45		0.60	0.018		0.024
C2	0.48		0.60	0.019		0.024
D	6.00		6.20	0.236		0.244
E	6.40		6.60	0.252		0.260
G	4.40		4.60	0.173		0.181
H	9.35		10.10	0.368		0.398
L2		0.8			0.031	
L4	0.60		1.00	0.024		0.039
V2	0°		8°	0°		0°



**DPAK FOOTPRINT**



**TUBE SHIPMENT (no suffix)\***



**TAPE AND REEL SHIPMENT (suffix "T4")\***

40 mm min. Access hole at slot location

Full radius

Tape slot in core for tape start 2.5mm min. width

**REEL MECHANICAL DATA**

DIM.	mm		inch	
	MIN.	MAX.	MIN.	MAX.
A		330		12.992
B	1.5		0.059	
C	12.8	13.2	0.504	0.520
D	20.2		0.795	
G	16.4	18.4	0.645	0.724
N	50		1.968	
T		22.4		0.881

BASE QTY	BULK QTY
2500	2500

**TAPE MECHANICAL DATA**

DIM.	mm		inch	
	MIN.	MAX.	MIN.	MAX.
A0	6.8	7	0.267	0.275
B0	10.4	10.6	0.409	0.417
B1		12.1		0.476
D	1.5	1.6	0.059	0.063
D1	1.5		0.059	
E	1.65	1.85	0.065	0.073
F	7.4	7.6	0.291	0.299
K0	2.55	2.75	0.100	0.108
P0	3.9	4.1	0.153	0.161
P1	7.9	8.1	0.311	0.319
P2	1.9	2.1	0.075	0.082
R	40		1.574	
W	15.7	16.3	0.618	0.641

TOP COVER TAPE

10 pitches cumulative tolerance on tape +/- 0.2 mm

Center line of cavity

User Direction of Feed

FEED DIRECTION

Bending radius R min.

\* on sales type

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